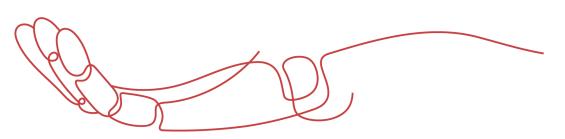




# **PRODUCT DATA SHEET**



To learn more about JGSEMI, please visit our website at







Datasheet

es Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.



Quad TVS Diode Array

### **Features**

Ultra low leakage: nA level

Operating voltage: 5V

Low clamping voltage

Complies with following standards:

- IEC 61000-4-2 (ESD) immunity test

Air discharge: ±25kV Contact discharge: ±16kV

- IEC61000-4-4 (EFT) 40A (5/50ns)

- IEC61000-4-5 (Lightning) 5A (8/20µs)

RoHS Compliant

## **Applications**

- USB 2.0 power and data line
- Set-top box and digital TV
- Digital video interface (DVI)
- Notebook Computers
- SIM Ports
- 10/100 Ethernet

## **Mechanical Characteristics**

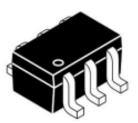
• Package: SOT-363

• Lead Finish: Lead Free

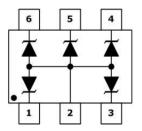
UL Flammability Classification Rating 94V-0

Quantity Per Reel:3,000pcs

Reel Size:7inch



**SOT-363** 



## Absolute Maximum Ratings(Tamb=25°C unless otherwise specified)

Parameter	Symbol	Value	Unit	
Peak Pulse Power (8/20µs)	Ррр	100	W	
ESD per IEC 61000-4-2 (Air)	\/===	±25	Kv	
ESD per IEC 61000-4-2 (Contact)	- <b>V</b> ESD	±16	r\v	
Operating Temperature Range	TJ	-55 to +125	°C	
Storage Temperature Range	Тѕтл	-55 to +150	$^{\circ}$	



## Electrical Characteristics (TA=25°C unless otherwise specified)

	$V_{\sf RWM}$	$V_{BR}$	Iτ	Iт Vc (mA) @1A	Vc		lπ	С
Part Number	(V)	(V)	(mA)		(Max)	(@A)	μΑ (Max)	(Pf) (Typ.)
ESDA6V1-5W6	5	6	1	9.8	12.5	5	1	50

### **Characteristic Curves**

Fig1. 8/20 µs Pulse Waveform

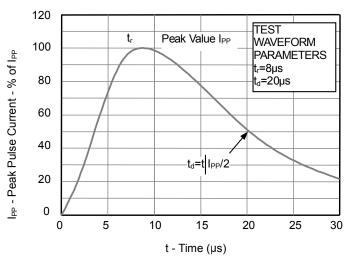


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

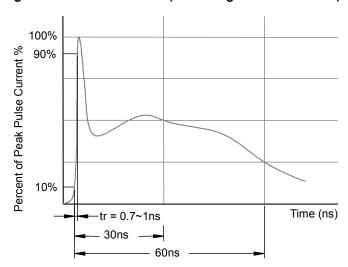
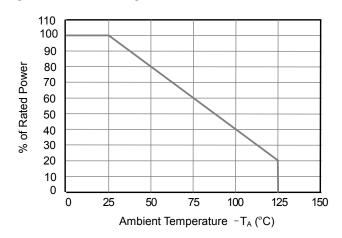
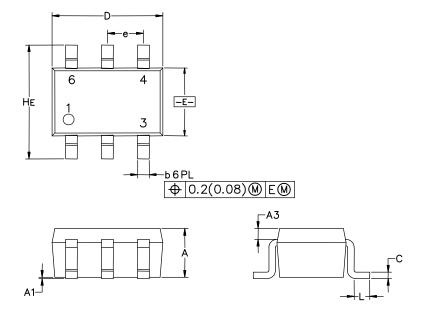


Fig3. Power Derating Curve



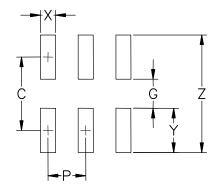


#### **SOT-363 Package Outline & Dimensions**



0		Inches		Millimeters			
Symbol	Min.	Nom.	Max.	Min.	Nom.	Max.	
Α	0.031	0.037	0.043	0.80	0.95	1.10	
A1	0.000	0.002	0.004	0.00	0.05	0.10	
A3	0.08 REF			0.2 REF			
b	0.004	0.008	0.012	0.10	0.21	0.30	
С	0.004	0.005	0.010	0.10	0.14	0.25	
D	0.070	0.078	0.086	1.80	2.00	2.20	
E	0.045	0.049	0.053	1.15	1.25	1.35	
е	0.026 BSC			0.65 BSC			
L	0.004	0.008	0.012	0.10	0.20	0.30	
HE	0.078	0.082	0.086	2.00	2.10	2.20	

### **Soldering Footprint**



Symbol	Inches	Millimeters		
С	0.0748	1.9		
G	0.055	1.40		
Р	0.025	0.65		
Х	0.0157	0.40		
Y	0.019	0.50		
Z	0.0945	2.4		



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